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(72) Inventors; and

(71) Applicants: **LALO, Cyril** [US/US]; 2243 Selby Avenue, Los Angeles, California 90064 (US). **POCHIC, Sebastien** [BE/BE]; Rue Auguste Lambiotte 28 #3, 1030 Schaerbeek (BE). **ESSEBAG, Jacques** [FR/FR]; 2 Avenue du President Wilson, 75116 Paris (FR).

(74) Agent: **COHEN, Michael**; 9025 Wilshire Blvd Suite 301, Beverly Hills, California 90211 (US).

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(54) Title: PACKAGED ELECTRONIC MODULE AND MANUFACTURING METHOD THEREOF

(57) Abstract: The present invention is a packaged electronic module with embedded electronics for use in smart cards. This invention assembles a plurality of electronics components on a flexible printed circuit, together with an integrated circuit chip and a contact plate, into a module. This module can then be embedded into a plastic card, using regular milling techniques, by a card manufacturer. This method packages the plurality of electronics components into a module. The present invention provides a business with the capability to avoid additional capital expenditure required for special equipment and enables all existing card manufacturers to manufacture smart cards with embedded electronics.



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